
2.4 GHz High-Linearity, High-Efficiency Power Amplifier

Features

- High Gain:
 - Typically 37 dB gain across 2.4–2.5 GHz over temperature -20°C to +85°C
- High linear output power:
 - >30 dBm P1dB
 - Please refer to [“Absolute Maximum Stress Ratings” on page 5](#)
 - Meets 802.11g OFDM spectrum mask requirement up to 28 dBm
 - Typically 25 dBm with <3% EVM, 802.11g, 54 Mbps
 - Typically 24 dBm with <2.5% EVM, 802.11n, MCS7-HT20, 50% duty cycle
 - Typically 24 dBm with <1.75% EVM, MCS9-HT40, 50% duty cycle
 - Meets 802.11b ACPR requirement up to 28 dBm
- High-speed power-up/down
 - Turn on/off time (10%-90%) <100 ns
- 10:1 VSWR survivability (unconditionally stable up to 28 dBm)
- On-chip power detection
 - >20 dB dynamic range
 - VSWR- and temperature-insensitive
- Simple input/output matching
- Packages available
 - 16-contact UQFN (3mm x 3mm)
 - Pin-to-pin compatible with SST12CP11
- All non-Pb (lead-free) devices are RoHS compliant

Applications

- WLAN (IEEE 802.11b/g/n)
- WLAN 256 QAM
- AP router
- WiMax (IEEE 802.16e)
- Home RF
- Cordless phones
- 2.4 GHz ISM wireless equipment

1.0 PRODUCT DESCRIPTION

SST12CP11C is a high-power and high-gain power amplifier (PA) based on the highly-reliable InGaP/GaAs HBT technology.

This PA can be easily configured for high-power applications with high power-added efficiency while operating over the 2.4-2.5 GHz frequency band. It typically provides 37 dB gain with 25% power-added efficiency @ $P_{OUT} = 28$ dBm for 802.11g.

SST12CP11C has excellent linearity, typically 25 dBm at 3% EVM with 54 Mbps 802.11g operation while meeting 802.11g spectrum mask at 28 dBm. SST12CP11C also has a single-ended power detector which lowers the users' cost for power control.

The power amplifier IC also features easy board-level usage along with high-speed power-up/-down control.

SST12CP11C is offered in 16-contact UQFN package. See [Figure 3-1](#) for pin assignments and [Table 4-1](#) for pin descriptions.

TO OUR VALUED CUSTOMERS

It is our intention to provide our valued customers with the best documentation possible to ensure successful use of your Microchip products. To this end, we will continue to improve our publications to better suit your needs. Our publications will be refined and enhanced as new volumes and updates are introduced.

If you have any questions or comments regarding this publication, please contact the Marketing Communications Department via E-mail at docerrors@microchip.com. We welcome your feedback.

Most Current Data Sheet

To obtain the most up-to-date version of this data sheet, please register at our Worldwide Web site at:

<http://www.microchip.com>

You can determine the version of a data sheet by examining its literature number found on the bottom outside corner of any page. The last character of the literature number is the version number, (e.g., DS30000000A is version A of document DS30000000).

Errata

An errata sheet, describing minor operational differences from the data sheet and recommended workarounds, may exist for current devices. As device/documentation issues become known to us, we will publish an errata sheet. The errata will specify the revision of silicon and revision of document to which it applies.

To determine if an errata sheet exists for a particular device, please check with one of the following:

- Microchip's Worldwide Web site; <http://www.microchip.com>
- Your local Microchip sales office (see last page)

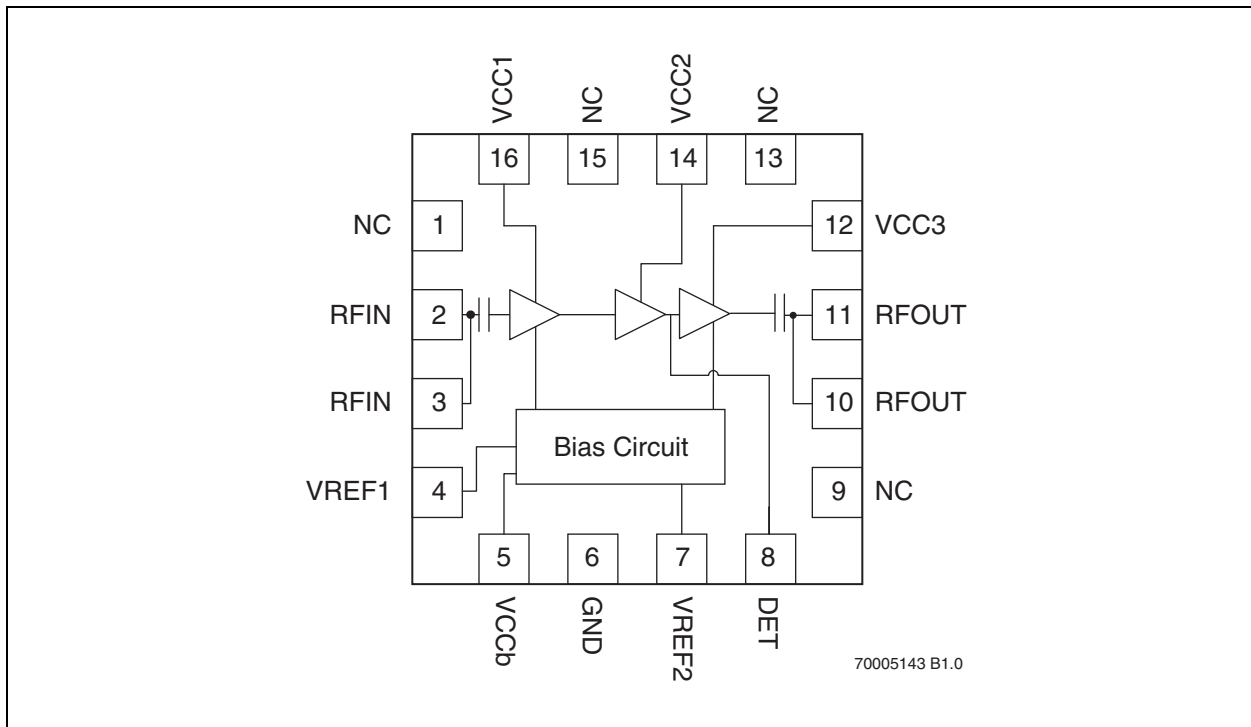
When contacting a sales office, please specify which device, revision of silicon and data sheet (include literature number) you are using.

Customer Notification System

Register on our web site at www.microchip.com to receive the most current information on all of our products.

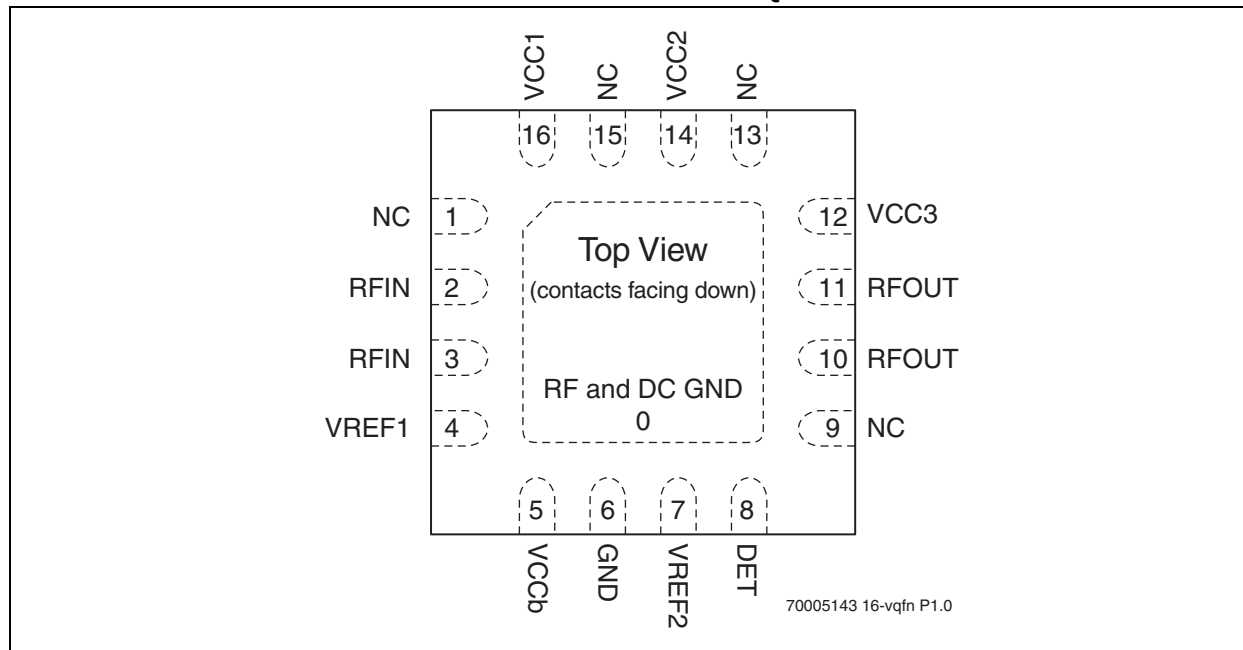
2.0 FUNCTIONAL BLOCKS

FIGURE 2-1: FUNCTIONAL BLOCK DIAGRAM



3.0 PIN ASSIGNMENTS

FIGURE 3-1: PIN ASSIGNMENTS FOR 16-CONTACT UQFN



4.0 PIN DESCRIPTIONS

TABLE 4-1: PIN DESCRIPTION

Symbol	Pin No.	Pin Name	Type ¹	Function
GND	0	Ground		The center pad should be connected to RF ground with several low inductance, low resistance vias.
NC	1	No Connection		Unconnected pins.
RFIN	2		I	RF input, DC decoupled
RFIN	3		I	RF input, DC decoupled
VREF1	4	Power Supply	PWR	1 st stage, idle-current control
VCCb	5	Power Supply	PWR	Supply voltage for bias circuit
GND	6	Ground		
VREF2	7	Power supply	PWR	2 nd and 3 rd stage, idle-current control
DET	8		O	On-chip power detector
NC	9	No Connection		Unconnected pins.
RFOUT	10		O	RF output
RFOUT	11		O	RF output
VCC3	12	Power Supply	PWR	Power supply, 3rd stage
NC	13	No Connection		Unconnected pins.
VCC2	14	Power Supply	PWR	Power supply, 2nd stage
NC	15	No Connection		Unconnected pins.
VCC1	16	Power Supply	PWR	Power supply, 1st stage

1. I=Input, O=Output

5.0 ELECTRICAL SPECIFICATIONS

The DC and RF specifications for the power amplifier are specified below. Refer to [Table 5-2](#) for the DC voltage and current specifications.

Absolute Maximum Stress Ratings (Applied conditions greater than those listed under “Absolute Maximum Stress Ratings” may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these conditions or conditions greater than those defined in the operational sections of this data sheet is not implied. Exposure to absolute maximum stress rating conditions may affect device reliability.)

Input power to pin 2 and 3 (P_{IN}) -3 dBm
 Supply voltage at pins 5,12,14 and 16 (V_{CC}) +6 V
 Reference voltage to pin 4 (V_{REF1}) and pin 7 (V_{REF2}) +3.2 V
 DC supply current (I_{CC}) 650 mA
 Operating Temperature (T_A) -40°C to +85°C
 Storage Temperature (T_{STG}) -40°C to +120°C
 Maximum Junction Temperature (T_J) +150°C
 Surface Mount Solder Reflow Temperature 260°C for 10 seconds

TABLE 5-1: OPERATING RANGE

Range	Ambient Temp	V_{CC}
Industrial	-20°C to +85°C	3.3 to 5.0V

TABLE 5-2: DC ELECTRICAL CHARACTERISTICS AT 25°C

Symbol	Parameter	Min.	Typ	Max.	Unit
V_{CC}	Supply Voltage	3.3	5.0	5.5	V
I_{CC}	DC Current for 802.11g, 28 dBm		500		mA
	for 802.11b, 28 dBm		500		mA
I_{CQ}	Idle Current for 802.11g to meet EVM<3% @24.5 dBm, $V_{CC} = 5.0V$		280		mA
	Idle Current, $V_{CC} = 3.3V$		205		mA
V_{REG}	Reference Voltage see Figure 6-8 on page 10	2.9	2.95	3.1	V
I_{REG}	Reference Current		8		mA

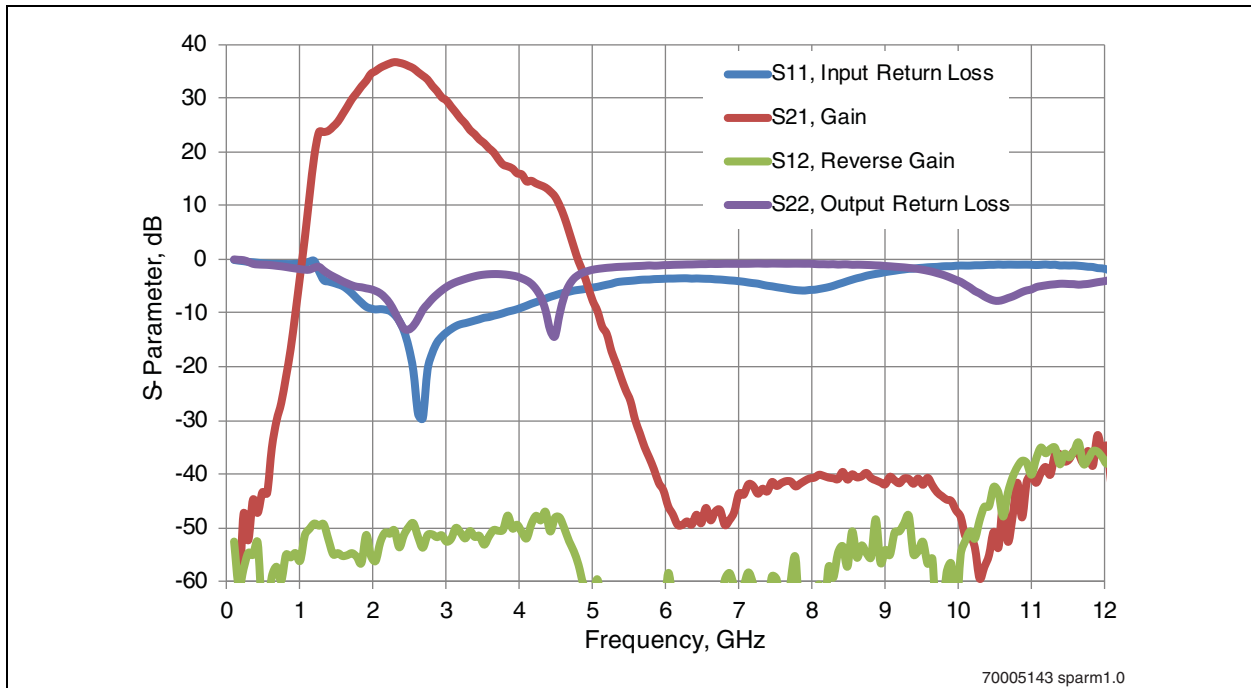
**TABLE 5-3: AC ELECTRICAL CHARACTERISTICS FOR CONFIGURATION AT $V_{CC} = 5V$,
 $V_{REF} = 2.95V$, 25°C, 50% DUTY CYCLE**

Symbol	Parameter	Min.	Typ	Max.	Unit
F_{L-U}	Frequency range in 802.11b/g applications	2400		2500	MHz
P_{OUT}	Output power at 3% EVM with 802.11g OFDM at 54 Mbps		25		dBm
	Output power at 2.5% EVM with 802.11n MCS7 HT20		24		dBm
	Output power at 1.75% EVM with 256 QAM MCS9 HT40		23.5		dBm
	Output power meeting 802.11g spectral mask		28		dBm
	Output power meeting 802.11n HT20 spectral mask		26		dBm
	Output power meeting MCS9-HT40 spectral mask		26		dBm
	Output power meeting 802.11b spectral mask		28		dBm
	Output power at 3% EVM with 802.11g, $V_{CC} = 3.3V$		20.5		dBm
G	Power gain for 802.11b/g/n/256 QAM	35	37		dB
	Power gain for 802.11b/g/n/256 QAM, $V_{CC} = 3.3V$		38		dB
G_{VAR}	Gain variation over band			±0.5	dB
2f	Second Harmonic at 28 dBm, 802.11b mask compliance		-15		dBm/MHz
	Second Harmonic at 26 dBm		-30		dBm/MHz
3f	Third Harmonic at 28 dBm, 802.11b mask compliance		-20		dBm/MHz
	Third Harmonic at 26 dBm		-50		dBm/MHz

6.0 TYPICAL PERFORMANCE CHARACTERISTICS

Test Conditions: $V_{CC} = 5.0V$, $V_{REG} = 2.95V$, $T_A = 25^\circ C$, unless otherwise specified

FIGURE 6-1: S-PARAMETERS



Test Conditions: $V_{CC} = 5.0V$, $V_{REG} = 2.95V$, $T_A = 25^\circ C$, IEEE 802.11g, 54 Mbps, 50% duty cycle unless otherwise specified

FIGURE 6-2: DYNAMIC EVM VERSUS OUTPUT POWER

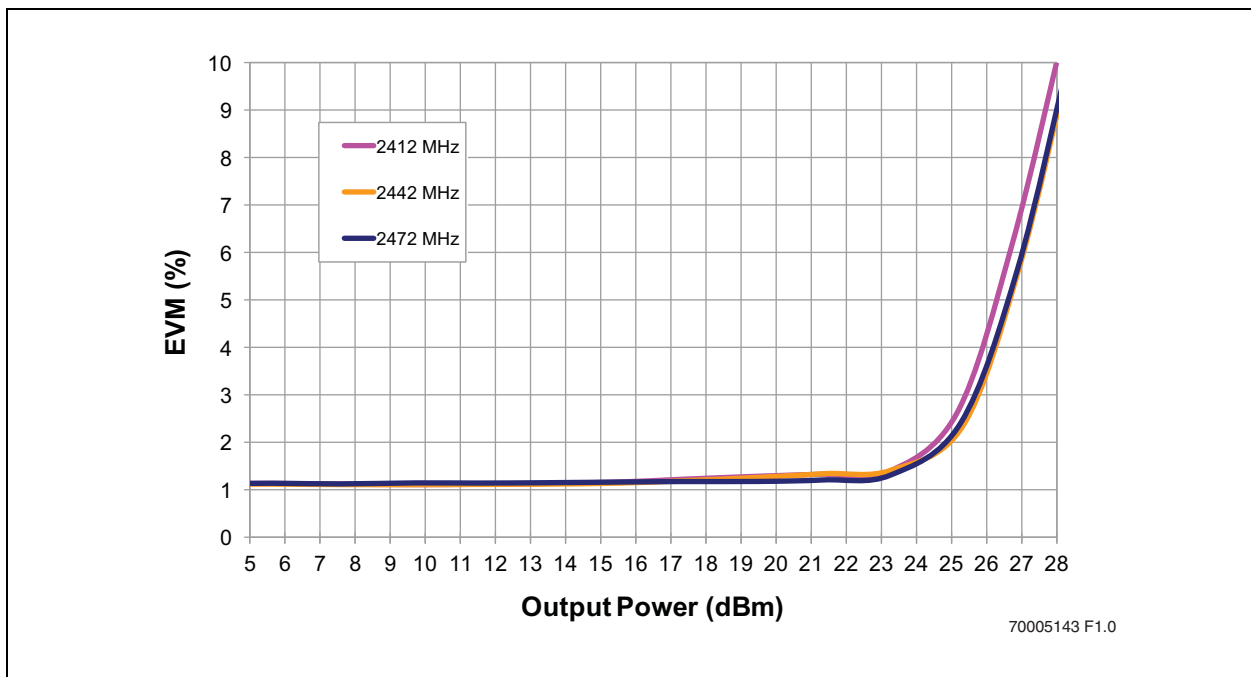


FIGURE 6-3: DYNAMIC EVM VERSUS OUTPUT POWER, WITH MCS7-20 MHz

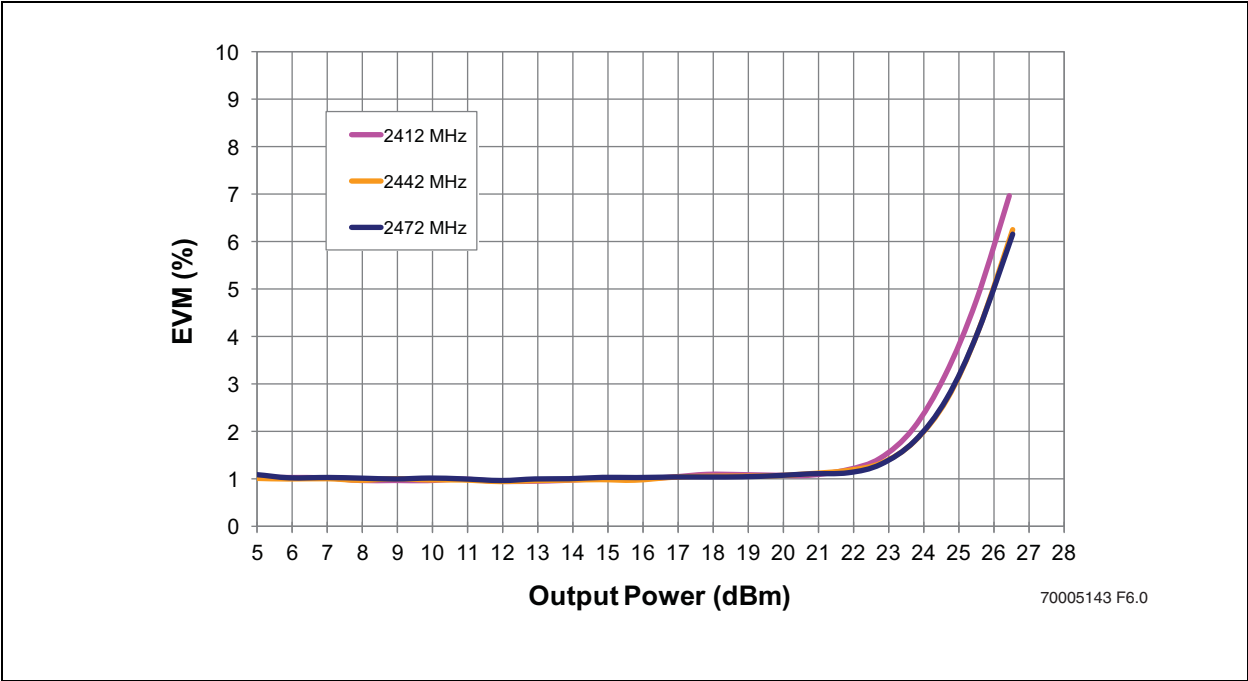


FIGURE 6-4: DYNAMIC EVM VERSUS OUTPUT POWER, WITH MCS9-40 MHz, 50% DUTY CYCLE

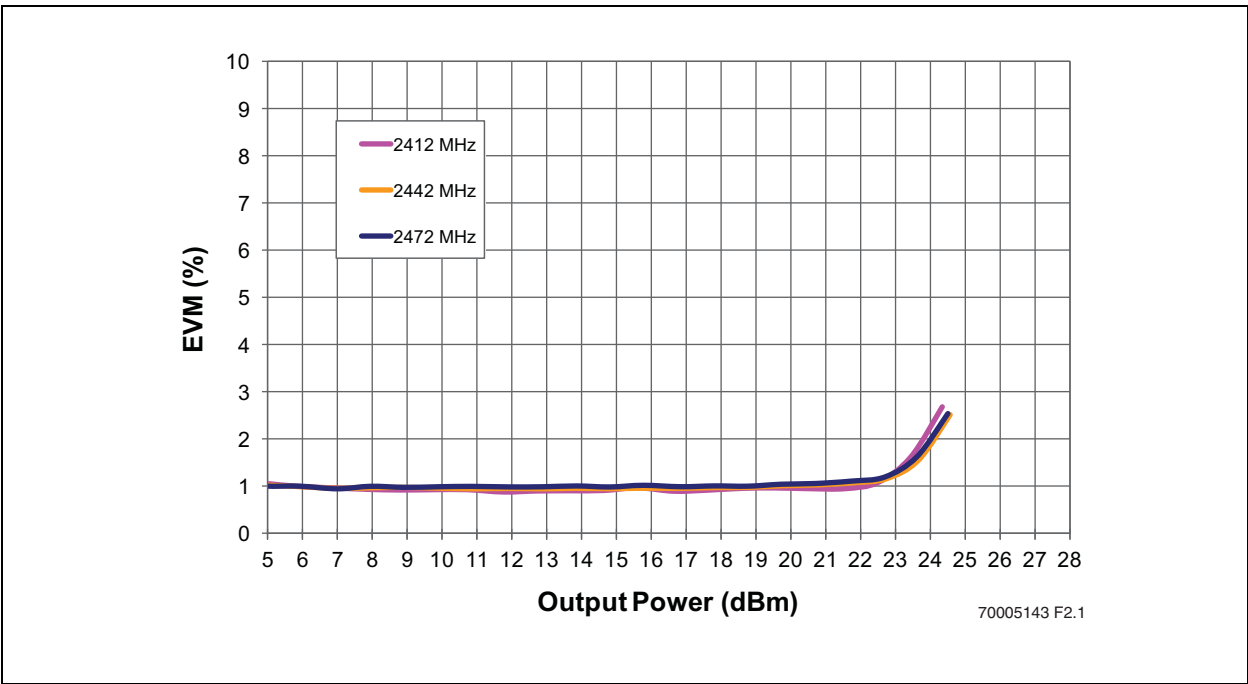


FIGURE 6-5: POWER GAIN VERSUS OUTPUT POWER

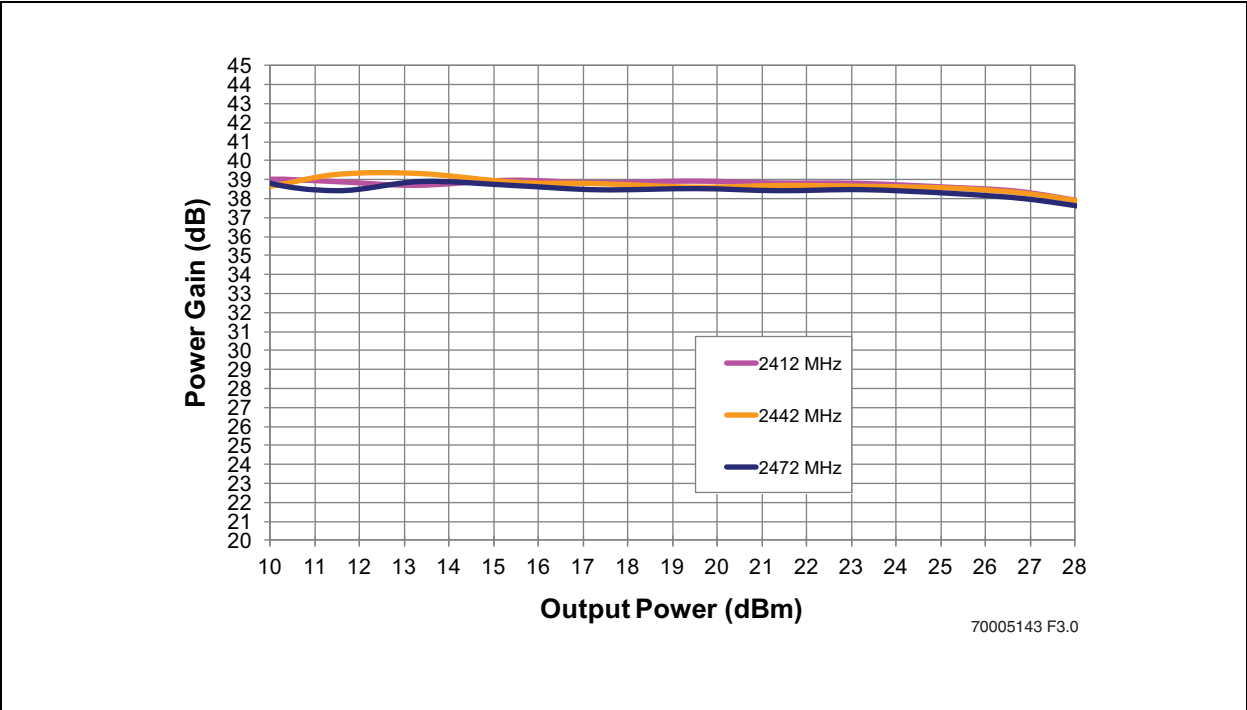


FIGURE 6-6: SUPPLY CURRENT VERSUS OUTPUT POWER

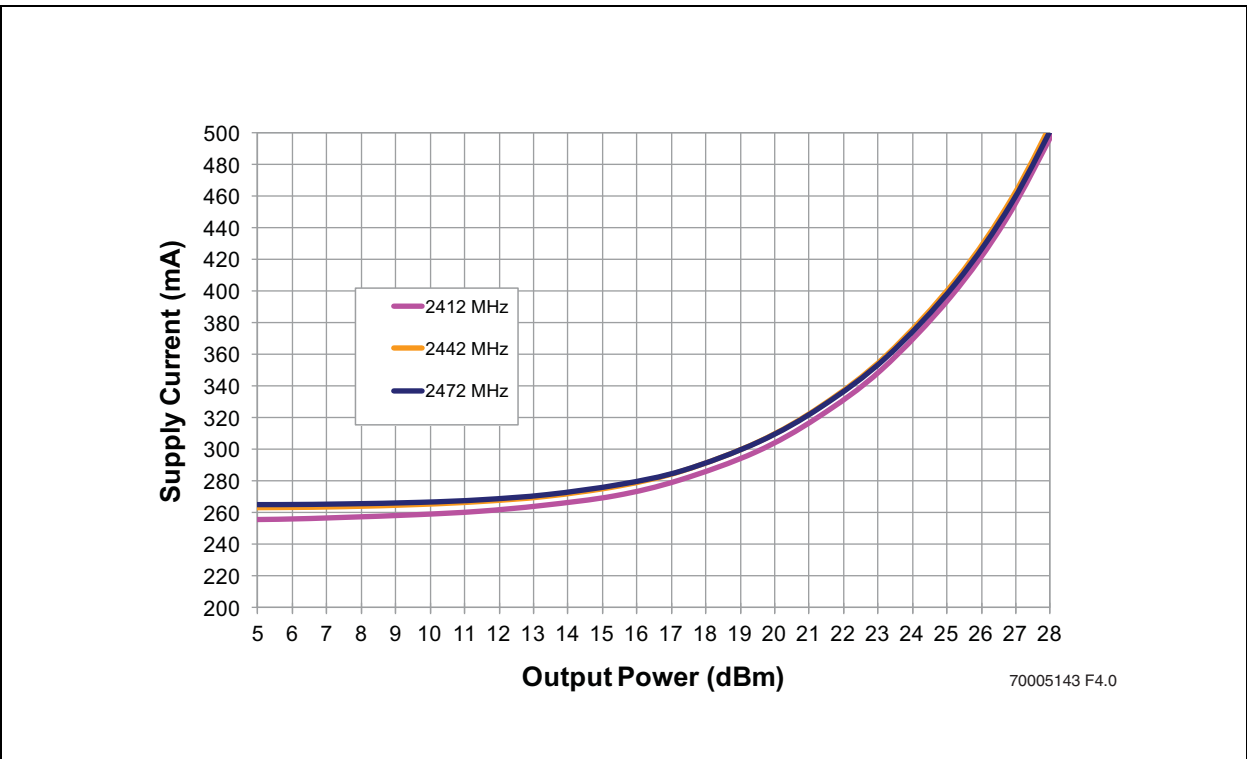


FIGURE 6-7: DETECTOR CHARACTERISTIC VERSUS OUTPUT POWER

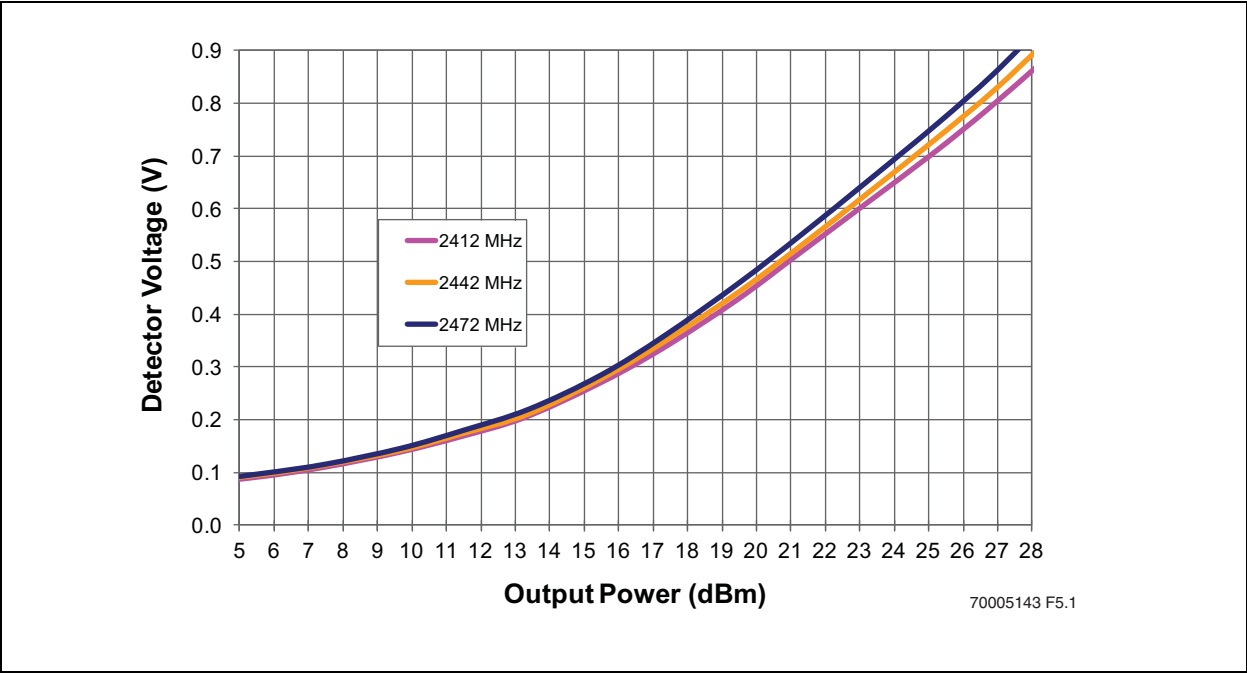
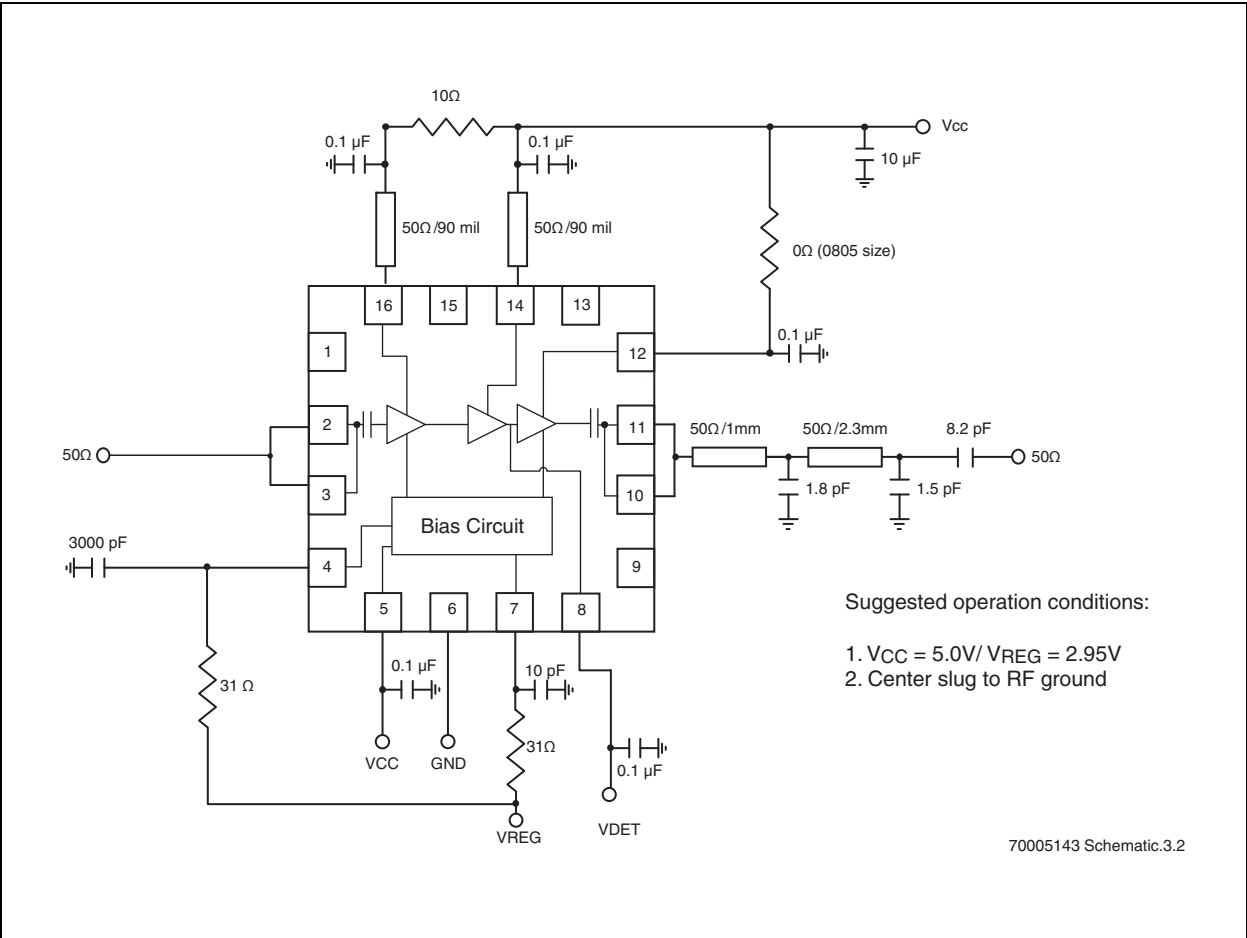


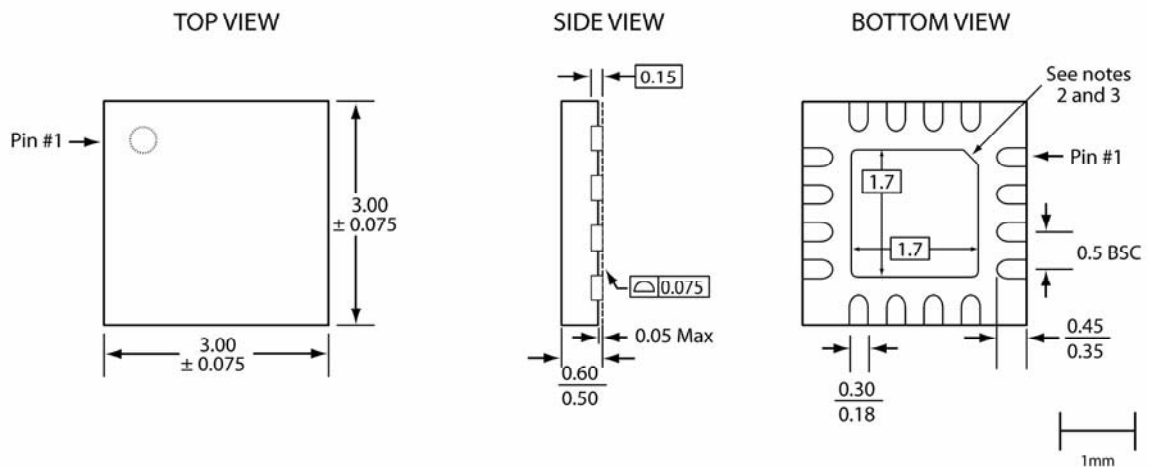
FIGURE 6-8: TYPICAL SCHEMATIC FOR 256 QAM APPLICATIONS



7.0 PACKAGING DIAGRAMS

16-Lead Ultra Thin Quad Flatpack No-Leads (QUCE/F) - 3x3 mm Body [UQFN]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



16-uqfn-3x3-QUC-0.0

Note:

1. Complies with JEDEC JEP95 MO-248D, variant UEED-4 except external paddle nominal dimensions.
2. From the bottom view, the pin #1 indicator may be either a 45-degree chamfer or a half-circle notch.
3. The external paddle is electrically connected to the die back-side and possibly to certain VSS leads. This paddle can be soldered to the PC board; it is suggested to connect this paddle to the VSS of the unit. Connection of this paddle to any other voltage potential can result in shorts and/or electrical malfunction of the device.
4. Untoleranced dimensions are nominal target dimensions.
5. All linear dimensions are in millimeters (max/min).

TABLE 7-1: REVISION HISTORY

Revision	Description	Date
A	• Initial release of data sheet	Apr 2014
B	• Revised Tables 5-1 , 5-2 , and 5-3 to reflect 3.3V information.	Feb 2015

THE MICROCHIP WEB SITE

Microchip provides online support via our WWW site at www.microchip.com. This web site is used as a means to make files and information easily available to customers. Accessible by using your favorite Internet browser, the web site contains the following information:

- **Product Support** – Data sheets and errata, application notes and sample programs, design resources, user's guides and hardware support documents, latest software releases and archived software
- **General Technical Support** – Frequently Asked Questions (FAQ), technical support requests, online discussion groups, Microchip consultant program member listing
- **Business of Microchip** – Product selector and ordering guides, latest Microchip press releases, listing of seminars and events, listings of Microchip sales offices, distributors and factory representatives

CUSTOMER CHANGE NOTIFICATION SERVICE

Microchip's customer notification service helps keep customers current on Microchip products. Subscribers will receive e-mail notification whenever there are changes, updates, revisions or errata related to a specified product family or development tool of interest.

To register, access the Microchip web site at www.microchip.com. Under "Support", click on "Customer Change Notification" and follow the registration instructions.

CUSTOMER SUPPORT

Users of Microchip products can receive assistance through several channels:

- Distributor or Representative
- Local Sales Office
- Field Application Engineer (FAE)
- Technical Support

Customers should contact their distributor, representative or Field Application Engineer (FAE) for support. Local sales offices are also available to help customers. A listing of sales offices and locations is included in the back of this document.

Technical support is available through the web site at: <http://microchip.com/support>

8.0 PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO. Device XXX Package	Device: SST12CP11C = 2.4 GHz High-Gain, High-Efficiency Power Amplifier Package: QUCE = UQFN (3mm x 3mm), 0.6 max thickness 16-contact Evaluation Kit K = Evaluation Kit Flag	Valid Combinations: SST12CP11C-QUCE SST12CP11C-QUCE-K
---	---	---

Note the following details of the code protection feature on Microchip devices:

- Microchip products meet the specification contained in their particular Microchip Data Sheet.
- Microchip believes that its family of products is one of the most secure families of its kind on the market today, when used in the intended manner and under normal conditions.
- There are dishonest and possibly illegal methods used to breach the code protection feature. All of these methods, to our knowledge, require using the Microchip products in a manner outside the operating specifications contained in Microchip's Data Sheets. Most likely, the person doing so is engaged in theft of intellectual property.
- Microchip is willing to work with the customer who is concerned about the integrity of their code.
- Neither Microchip nor any other semiconductor manufacturer can guarantee the security of their code. Code protection does not mean that we are guaranteeing the product as "unbreakable."

Code protection is constantly evolving. We at Microchip are committed to continuously improving the code protection features of our products. Attempts to break Microchip's code protection feature may be a violation of the Digital Millennium Copyright Act. If such acts allow unauthorized access to your software or other copyrighted work, you may have a right to sue for relief under that Act.

Information contained in this publication regarding device applications and the like is provided only for your convenience and may be superseded by updates. It is your responsibility to ensure that your application meets with your specifications. MICROCHIP MAKES NO REPRESENTATIONS OR WARRANTIES OF ANY KIND WHETHER EXPRESS OR IMPLIED, WRITTEN OR ORAL, STATUTORY OR OTHERWISE, RELATED TO THE INFORMATION, INCLUDING BUT NOT LIMITED TO ITS CONDITION, QUALITY, PERFORMANCE, MERCHANTABILITY OR FITNESS FOR PURPOSE. Microchip disclaims all liability arising from this information and its use. Use of Microchip devices in life support and/or safety applications is entirely at the buyer's risk, and the buyer agrees to defend, indemnify and hold harmless Microchip from any and all damages, claims, suits, or expenses resulting from such use. No licenses are conveyed, implicitly or otherwise, under any Microchip intellectual property rights.

Trademarks

The Microchip name and logo, the Microchip logo, dsPIC, FlashFlex, flexPWR, JukeBlox, KEELoQ, KEELoQ logo, Klear, LANCheck, MediaLB, MOST, MOST logo, MPLAB, OptoLyzer, PIC, PICSTART, PIC³² logo, RightTouch, SpyNIC, SST, SST Logo, SuperFlash and UNI/O are registered trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

The Embedded Control Solutions Company and mTouch are registered trademarks of Microchip Technology Incorporated in the U.S.A.

Analog-for-the-Digital Age, BodyCom, chipKIT, chipKIT logo, CodeGuard, dsPICDEM, dsPICDEM.net, ECAN, In-Circuit Serial Programming, ICSP, Inter-Chip Connectivity, KlearNet, KlearNet logo, MiWi, MPASM, MPF, MPLAB Certified logo, MPLIB, MPLINK, MultiTRAK, NetDetach, Omniscient Code Generation, PICDEM, PICDEM.net, PICKit, PICtail, RightTouch logo, REAL ICE, SQI, Serial Quad I/O, Total Endurance, TSHARC, USBCheck, VariSense, ViewSpan, WiperLock, Wireless DNA, and ZENA are trademarks of Microchip Technology Incorporated in the U.S.A. and other countries.

SQTP is a service mark of Microchip Technology Incorporated in the U.S.A.

Silicon Storage Technology is a registered trademark of Microchip Technology Inc. in other countries.

GestIC is a registered trademarks of Microchip Technology Germany II GmbH & Co. KG, a subsidiary of Microchip Technology Inc., in other countries.

All other trademarks mentioned herein are property of their respective companies.

© 2014, Microchip Technology Incorporated, Printed in the U.S.A., All Rights Reserved.

ISBN:978-1-63277-067-7

**QUALITY MANAGEMENT SYSTEM
CERTIFIED BY DNV
= ISO/TS 16949 =**

Microchip received ISO/TS-16949:2009 certification for its worldwide headquarters, design and wafer fabrication facilities in Chandler and Tempe, Arizona; Gresham, Oregon and design centers in California and India. The Company's quality system processes and procedures are for its PIC® MCUs and dsPIC® DSCs, KEELoQ® code hopping devices, Serial EEPROMs, microperipherals, nonvolatile memory and analog products. In addition, Microchip's quality system for the design and manufacture of development systems is ISO 9001:2000 certified.

World Wide Sales and Service

AMERICAS

Corporate Office
 2355 West Chandler Blvd.
 Chandler, AZ 85224-6199
 Tel: 480-792-7200
 Fax: 480-792-7277
 Technical Support:
<http://www.microchip.com/support>
 Web Address:
www.microchip.com

Atlanta
 Duluth, GA
 Tel: 678-957-9614
 Fax: 678-957-1455

Austin, TX
 Tel: 512-257-3370

Boston
 Westborough, MA
 Tel: 774-760-0087
 Fax: 774-760-0088

Chicago
 Itasca, IL
 Tel: 630-285-0071
 Fax: 630-285-0075

Cleveland
 Independence, OH
 Tel: 216-447-0464
 Fax: 216-447-0643

Dallas
 Addison, TX
 Tel: 972-818-7423
 Fax: 972-818-2924

Detroit
 Novi, MI
 Tel: 248-848-4000

Houston, TX
 Tel: 281-894-5983
 Indianapolis

Noblesville, IN
 Tel: 317-773-8323
 Fax: 317-773-5453

Los Angeles
 Mission Viejo, CA
 Tel: 949-462-9523
 Fax: 949-462-9608

New York, NY
 Tel: 631-435-6000

San Jose, CA
 Tel: 408-735-9110

Canada - Toronto
 Tel: 905-673-0699
 Fax: 905-673-6509

ASIA/PACIFIC

Asia Pacific Office
 Suites 3707-14, 37th Floor
 Tower 6, The Gateway
 Harbour City, Kowloon

Hong Kong
 Tel: 852-2943-5100
 Fax: 852-2401-3431

Australia - Sydney
 Tel: 61-2-9868-6733
 Fax: 61-2-9868-6755

China - Beijing
 Tel: 86-10-8569-7000
 Fax: 86-10-8528-2104

China - Chengdu
 Tel: 86-28-8665-5511
 Fax: 86-28-8665-7889

China - Chongqing
 Tel: 86-23-8980-9588
 Fax: 86-23-8980-9500

China - Dongguan
 Tel: 86-769-8702-9880

China - Hangzhou
 Tel: 86-571-8792-8115
 Fax: 86-571-8792-8116

China - Hong Kong SAR
 Tel: 852-2943-5100
 Fax: 852-2401-3431

China - Nanjing
 Tel: 86-25-8473-2460
 Fax: 86-25-8473-2470

China - Qingdao
 Tel: 86-532-8502-7355
 Fax: 86-532-8502-7205

China - Shanghai
 Tel: 86-21-5407-5533
 Fax: 86-21-5407-5066

China - Shenyang
 Tel: 86-24-2334-2829
 Fax: 86-24-2334-2393

China - Shenzhen
 Tel: 86-755-8864-2200
 Fax: 86-755-8203-1760

China - Wuhan
 Tel: 86-27-5980-5300
 Fax: 86-27-5980-5118

China - Xian
 Tel: 86-29-8833-7252
 Fax: 86-29-8833-7256

ASIA/PACIFIC

China - Xiamen
 Tel: 86-592-2388138
 Fax: 86-592-2388130

China - Zhuhai
 Tel: 86-756-3210040
 Fax: 86-756-3210049

India - Bangalore
 Tel: 91-80-3090-4444
 Fax: 91-80-3090-4123

India - New Delhi
 Tel: 91-11-4160-8631
 Fax: 91-11-4160-8632

India - Pune
 Tel: 91-20-3019-1500

Japan - Osaka
 Tel: 81-6-6152-7160
 Fax: 81-6-6152-9310

Japan - Tokyo
 Tel: 81-3-6880-3770
 Fax: 81-3-6880-3771

Korea - Daegu
 Tel: 82-53-744-4301
 Fax: 82-53-744-4302

Korea - Seoul
 Tel: 82-2-554-7200
 Fax: 82-2-558-5932 or
 82-2-558-5934

Malaysia - Kuala Lumpur
 Tel: 60-3-6201-9857
 Fax: 60-3-6201-9859

Malaysia - Penang
 Tel: 60-4-227-8870
 Fax: 60-4-227-4068

Philippines - Manila
 Tel: 63-2-634-9065
 Fax: 63-2-634-9069

Singapore
 Tel: 65-6334-8870
 Fax: 65-6334-8850

Taiwan - Hsin Chu
 Tel: 886-3-5778-366
 Fax: 886-3-5770-955

Taiwan - Kaohsiung
 Tel: 886-7-213-7828

Taiwan - Taipei
 Tel: 886-2-2508-8600
 Fax: 886-2-2508-0102

Thailand - Bangkok
 Tel: 66-2-694-1351
 Fax: 66-2-694-1350

EUROPE

Austria - Wels
 Tel: 43-7242-2244-39
 Fax: 43-7242-2244-393

Denmark - Copenhagen
 Tel: 45-4450-2828
 Fax: 45-4485-2829

France - Paris
 Tel: 33-1-69-53-63-20
 Fax: 33-1-69-30-90-79

Germany - Dusseldorf
 Tel: 49-2129-3766400

Germany - Munich
 Tel: 49-89-627-144-0
 Fax: 49-89-627-144-44

Germany - Pforzheim
 Tel: 49-7231-424750

Italy - Milan
 Tel: 39-0331-742611
 Fax: 39-0331-466781

Italy - Venice
 Tel: 39-049-7625286

Netherlands - Drunen
 Tel: 31-416-690399
 Fax: 31-416-690340

Poland - Warsaw
 Tel: 48-22-3325737

Spain - Madrid
 Tel: 34-91-708-08-90
 Fax: 34-91-708-08-91

Sweden - Stockholm
 Tel: 46-8-5090-4654

UK - Wokingham
 Tel: 44-118-921-5800
 Fax: 44-118-921-5820

Компания «Life Electronics» занимается поставками электронных компонентов импортного и отечественного производства от производителей и со складов крупных дистрибьюторов Европы, Америки и Азии.

С конца 2013 года компания активно расширяет линейку поставок компонентов по направлению коаксиальный кабель, кварцевые генераторы и конденсаторы (керамические, пленочные, электролитические), за счёт заключения дистрибьюторских договоров

Мы предлагаем:

- Конкурентоспособные цены и скидки постоянным клиентам.
- Специальные условия для постоянных клиентов.
- Подбор аналогов.
- Поставку компонентов в любых объемах, удовлетворяющих вашим потребностям.
- Приемлемые сроки поставки, возможна ускоренная поставка.
- Доставку товара в любую точку России и стран СНГ.
- Комплексную поставку.
- Работу по проектам и поставку образцов.
- Формирование склада под заказчика.
- Сертификаты соответствия на поставляемую продукцию (по желанию клиента).
- Тестирование поставляемой продукции.
- Поставку компонентов, требующих военную и космическую приемку.
- Входной контроль качества.
- Наличие сертификата ISO.

В составе нашей компании организован Конструкторский отдел, призванный помогать разработчикам, и инженерам.

Конструкторский отдел помогает осуществить:

- Регистрацию проекта у производителя компонентов.
- Техническую поддержку проекта.
- Защиту от снятия компонента с производства.
- Оценку стоимости проекта по компонентам.
- Изготовление тестовой платы монтаж и пусконаладочные работы.



Тел: +7 (812) 336 43 04 (многоканальный)

Email: org@lifeelectronics.ru

www.lifeelectronics.ru